

$$\begin{aligned} & \int_{-\infty}^{\infty} \delta(x) \delta(x) dx = \int_{-\infty}^{\infty} \delta(x) dx = 1 \\ & \int_{-\infty}^{\infty} \delta(x) \delta(x) dx = \int_{-\infty}^{\infty} \delta(x) dx = 1 \end{aligned}$$

Series Editor

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Preface

The first part of the book is devoted to the study of the properties of the function $f(x)$ defined by the equation $f(x) = x + f(x^2)$. It is shown that the function $f(x)$ is continuous and differentiable at the point $x = 1$. The second part of the book is devoted to the study of the properties of the function $f(x)$ defined by the equation $f(x) = x + f(x^2)$. It is shown that the function $f(x)$ is continuous and differentiable at the point $x = 1$. The third part of the book is devoted to the study of the properties of the function $f(x)$ defined by the equation $f(x) = x + f(x^2)$. It is shown that the function $f(x)$ is continuous and differentiable at the point $x = 1$.

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$$\frac{1}{x^2} + \frac{1}{x^3} + \frac{1}{x^4} + \dots + \frac{1}{x^{2n}} + \dots$$

$$\frac{1}{x^2} + \frac{1}{x^3} + \frac{1}{x^4} + \dots + \frac{1}{x^{2n}} + \dots$$

Series Preface

The series consists of 10 volumes, each containing a collection of papers from the International Congress of Mathematicians (ICM) held in 1982 in Warsaw, Poland. The volumes are arranged in two groups of five, with the first group containing the papers of the first four days and the second group containing the papers of the last four days. The papers are arranged in chronological order within each day, and the volumes are arranged in chronological order of the days. The series is published by the American Mathematical Society (AMS) and the Polish Academy of Sciences (PAN). The series is a valuable resource for mathematicians and students alike, providing a comprehensive overview of the state of the field in 1982. The series is also a historical record of the work of some of the most prominent mathematicians of the 20th century. The series is available in both print and electronic formats. The print format is available in hardcover and paperback, and the electronic format is available in PDF and HTML. The series is a must-read for anyone interested in the history of mathematics or the work of the great mathematicians of the 20th century.

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S.W.R. Lee $\frac{1}{2}x^2 + \frac{1}{3}x^3 + \frac{1}{4}x^4 + \frac{1}{5}x^5 + \frac{1}{6}x^6 + \frac{1}{7}x^7 + \frac{1}{8}x^8 + \frac{1}{9}x^9 + \frac{1}{10}x^{10} + \dots$

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